Abstract of the Disclosure

A method and apparatus including gluing vias in the closure surface and/or the recording module surface to increase bonding strength of the closure to the recording module. The surface of the recording module has a nonplanar topography along a gap side surface which creates localized air space in the gap. When adhesive is introduced between the closure and the recording module, the adhesive flows into these air spaces to bond the surfaces. The invention utilizes gluing vias in the surfaces of the closure and/or the recording module to increase flow of the adhesive and improve bonding strength.